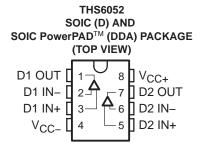
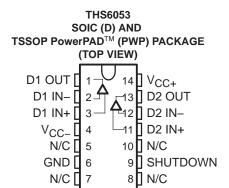
- **Remote Terminal ADSL Line Driver**
 - Ideal for Both Full Rate ADSL and G.Lite
 - Compatible With 1:1 Transformer Ratio
- Low 2.7 pA/√Hz Noninverting Current Noise
 - Reduces Noise Feedback Through **Hybrid Into Downstream Channel**
- Wide Supply Voltage Range ± 5 V to ± 15 V
 - Ideal for ±12-V Operation
- **Wide Output Swing**
 - 42 Vpp Differential Output Voltage, $R_1 = 200 \Omega, \pm 12-V$ Supply
- **High Output Current**
 - 175 mA (typ)

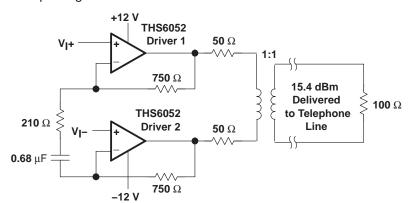


- **High Speed**
 - 110 MHz (-3 dB, G=8, ±12 V)
 - 1500 V/ μ s Slew Rate (G = 8, \pm 12 V)
- Low Distortion, Single-Ended, G = 8
 - 83 dBc (250 kHz, 2 Vpp, 100-Ω load)
- Low Power Shutdown (THS6053)
 - 300-μA Total Standby Current
- **Thermal Shutdown and Short Circuit** Protection
- Standard SOIC, SOIC PowerPAD, and TSSOP PowerPAD™ Package
- **Evaluation Module Available**



description

The THS6052/3 is a high-speed line driver ideal for driving signals from the remote terminal to the central office in asymmetrical digital subscriber line (ADSL) applications. It can operate from ±12-V supply voltages while drawing only 5.2 mA of supply current per channel. It offers low -83 dBc total harmonic distortion driving a 100- Ω load (2 Vpp). The THS6052/3 offers a high 42-Vpp differential output swing across a 200- Ω load from a \pm 12-V supply. The THS6053 features a low-power shutdown mode, consuming only 300 μA quiescent current per channel. The THS6052/3 is packaged in a standard SOIC. SOIC PowerPAD™, and TSSOP PowerPAD™ packages.



RELATED PRODUCTS

DEVICE	DESCRIPTION
THS6042/3	350-mA, ±12 ADSL CPE line driver
THS6092/3	275-mA, +12 V ADSL CPE line driver
OPA2677	380-mA, +12 V ADSL CPE line driver
THS6062	Low noise ADSL receiver



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerPAD is a trademark of Texas Instruments.



AVAILABLE OPTION

		PACKAGED DEVICE						
TA	SOIC-8 (D)	SOIC-8 PowerPAD (DDA)	SOIC-14 (D)	TSSOP-14 (PWP)	EVALUATION MODULES			
0°C to 70°C	THS6052CD	THS6052CDDA	THS6053CD	THS6053CPWP	THS6052EVM THS6053EVM			
-40°C to 85°C	THS6052ID	THS6052IDDA	THS6053ID	THS6053IPWP	_			

absolute maximum ratings over operating free-air temperature (unless otherwise noted)

Supply voltage, V _{CC+} to V _{CC-}	33 V
Input voltage	± V _{CC}
Output current (see Note 1)	
Differential input voltage	± 4 V
Maximum junction temperature	150°C
Total power dissipation at (or below) 25°C free-air temperature	See Dissipation Ratings Table
Operating free-air temperature, T _A : Commercial	0°C to 70°C
Industrial	40°C to 85°C
Storage temperature, T _{stq} : Commercial	65°C to 125°C
Industrial	65°C to 125°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	300°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The THS6052 and THS6053 may incorporate a PowerPAD™ on the underside of the chip. This acts as a heatsink and must be connected to a thermally dissipating plane for proper power dissipation. Failure to do so may result in exceeding the maximum junction temperature which could permanently damage the device. See TI technical brief SLMA002 for more information about utilizing the PowerPAD™ thermally enhanced package.

DISSIPATION RATING TABLE

PACKAGE	AL^{θ}	θЈС	T _A = 25°C T _J = 150°C POWER RATING
D-8	95°C/W‡	38.3°C/W‡	1.32 W
DDA	45.8°C/W‡	9.2°C/W‡	2.73 W
D-14	66.6°C/W [‡]	26.9°C/W [‡]	1.88 W
PWP	37.5°C/W	1.4°C/W	3.3 W

[‡] This data was taken using the JEDEC proposed high-K test PCB. For the JEDEC low-K test PCB, the $\Theta_{\mbox{\scriptsize JA}}$ is168°C/W for the D–8 package and 122.3°C/W for the D–14 package.

recommended operating conditions

		MIN	NOM MAX	UNIT
Cumply valle as No 40 No	Dual supply	±5	±15	.,
Supply voltage, V _{CC+} to V _{CC-}	Single supply	10	30	V
	C-suffix	0	70	
Operating free-air temperature, T _A	I-suffix	-40	85	°C



electrical characteristics over recommended operating free-air temperature range, T_A = 25°C, V_{CC} = \pm 12 V, R_{FEEDBACK} = 750 Ω , R_L = 100 Ω (unless otherwise noted)

dynamic performance

	PARAMETER		TEST CONDITIO	NS	MIN	TYP	MAX	UNIT
			C 4 B- 4 I-O	V _{CC} = ±5 V	110			
		D 500	$G=1$, $R_F=1$ $k\Omega$	V _{CC} = ±12 V		120		
		R _L = 50 Ω	G= 2, $R_F = 680 \Omega$	V 15V 140V		100		
DIA	Omell simulate and vide (O dD)		G= 8, R _F = 330 Ω	$V_{CC} = \pm 5 \text{ V}, \pm 12 \text{ V}$		90		
BW	Small-signal bandwidth (–3 dB)	R _L = 100 Ω	G= 1, R _F = 1 kΩ	V _{CC} = ±5 V		150		MHz
				V _{CC} = ±12 V		170		
			G= 2, R _F = 680Ω	V _{CC} = ±5 V, ±12 V		135		
			G = 8, R_F = 330 $Ω$			110		
			V _{CC} = ±5 V	V _{CC} = ±5 V		650		
		V _O = 4 V _{PP}	V _{CC} = ±12 V	V _{CC} = ±12 V		850		
SR	Slew rate (see Note 2), G=8		V _{CC} = ±15 V	V _{CC} = ±15 V		950		V/μs
		V _O = 16 V _{PP}	V _{CC} = ±12 V	V _{CC} = ±12 V		1500		
			$V_{CC} = \pm 15 \text{ V}$	$V_{CC} = \pm 15 \text{ V}$		1700		

NOTE 2: Slew rate is defined from the 25% to the 75% output levels.

noise/distortion performance

	PARAMETER		1	EST CONDITIO	NS	MIN 7	ГҮР	MAX	UNIT
		Total harmonic distortion (single-ended		$R_L = 100 \Omega$,	V _{O(pp)} = 2 V		-83		
THD	Total harmonic distortion (sir			f = 250 kHz	V _{O(pp)} = 16 V		-78		dD.
THU	configuration)		Gain = 8, $V_{CC} = \pm 5 \text{ V},$	$R_L = 50 \Omega$,	V _{O(pp)} = 2 V		-74		dBc
				f = 250 kHz	V _{O(pp)} = 6 V		-72		
V _n	Input voltage noise		V _{CC} = ±5 V, ±12 V	f = 10 kHz ,			2.1		nV/√ Hz
		+Input	f = 10 kHz,	$V_{CC} = \pm 5 \text{ V},$			2.7		
l'n	Input current noise	-Input]	$V_{CC} = \pm 12 \text{ V},$ $V_{CC} = \pm 15 \text{ V}$		1	10.7		pA/√Hz
,	0 1 1		f = 250 kHz, G = 2,	$V_{CC} = \pm 12 \text{ V},$ $R_L = 100 \Omega$	V _O = 2 Vp-p		-79		
XT	Crosstalk		f = 250 kHz, G = 2,	$V_{CC} = \pm 5 \text{ V},$ $R_L = 50 \Omega$	V _O = 2 Vp-p		-71		dBc

THS6052, THS6053 175 mA, \pm 12 V ADSL CPE LINE DRIVERS

SLOS293D - JUNE 2000 - REVISED DECEMBER 2001

electrical characteristics over recommended operating free-air temperature range, T_A = 25°C, V_{CC} = \pm 12 V, R_{FEEDBACK} = 750 Ω , R_L = 100 Ω (unless otherwise noted) (continued)

dc performance

	PARAMETER	TEST CONI	DITIONS	MIN	TYP	MAX	UNIT
	hand Mark allows		T _A = 25°C		5	10	
Vos	Input offset voltage		T _A = full range			15	
	Differential offect value	$V_{CC} = \pm 12 \text{ V},$ $V_{CC} = \pm 6 \text{ V}$	T _A = 25°C		3	6	mV
	Differential offset voltage	-	T _A = full range			8	
	Offset drift		T _A = full range			30	μV/°C
	- Input bias current	V _{CC} = ±12 V, V _{CC} = ±6 V	T _A = 25°C		5	10	
			T _A = full range			12	
l	. Janut higo gurrant		T _A = 25°C		2	5	^
^I IB	+ Input bias current		T _A = full range			6	μΑ
	Differential insult him assument		T _A = 25°C		5	10	
	Differential input bias current		T _A = full range			12	
Z _{OL}	Open loop transimpedance	$V_{CC} = \pm 12 \text{ V},$ $V_{CC} = \pm 6 \text{ V}$	$R_L = 1 \text{ k}\Omega$,		1		$M\Omega$

input characteristics

	PARAMETER		TEST CONDITIONS		TYP	MAX	UNIT
.,	lanut accessos anada valtaria nana	$V_{CC} = \pm 12 \text{ V}$		±9.7	±10.1		
VICR	Input common-mode voltage range	V _C C = ±6 V	±3.8	±4.2		V	
CMRR	Common-mode rejection ratio $ V_{CC} = \pm 12 \text{ V}, $ $ V_{CC} = \pm 6 \text{ V} $	T _A = 25°C	59	66		dB	
CIVIKK	Common-mode rejection ratio	$VCC = \pm 6 V$	T _A = full range	57			uБ
_	land assistance	+ Input			1.5		$M\Omega$
R _I	Input resistance	- Input			15		Ω
Cl	Input capacitance				2		pF

output characteristics

	PARAMETER		TEST C	CONDITIONS	MIN	TYP	MAX	UNIT
			$R_L = 50 \Omega$,	$V_{CC} = \pm 6 V$	±4.2	±4.6		
٧o	Output voltage swing	Single ended	Single ended $R_L = 100 \Omega$	$V_{CC} = \pm 12 \text{ V}$	±10.1	±10.5		V
				$V_{CC} = \pm 6 V$	±4.4	±4.8		
1-	Output ourrant		$R_L = 25 \Omega$,	$V_{CC} = \pm 12 \text{ V}$	150	175		mA
10	Output current		$R_L = 10 \Omega$,	$V_{CC} = \pm 6 \text{ V}$	150	175		IIIA
ISC	Short-circuit current		$R_L = 0 \Omega$,	$V_{CC} = \pm 12 \text{ V}$		250		mA
	Output resistance		Open loop			14		Ω



electrical characteristics over recommended operating free-air temperature range, T_A = 25°C, V_{CC} = ± 12 V, R_{FEEDBACK} = 750 Ω , R_L = 100 Ω (unless otherwise noted) (continued)

power supply

	PARAMETER			TEST CONDITIONS		TYP	MAX	UNIT
.,	Dual sup				±4.5		±16.5	.,
VCC	Operating range	Single supply					33	V
			V 140 V	T _A = 25°C		5.2	7	
loo			$V_{CC} = \pm 12 \text{ V}$	T _A = full range			8	mA
lcc	Quiescent current (each driver)			T _A = 25°C		4.5	6.5	
			$VCC = \pm 6 V$	T _A = full range			7.5	
			V 140 V	T _A = 25°C	-64	-62		
DODD	Development and a street and a		$V_{CC} = \pm 12 \text{ V}$	T _A = full range	-61	-		-ID
PSRR	Power supply rejection ratio		V _{CC} = ±6 V	T _A = 25°C	-60	-70		dB
				T _A = full range	-58			

shutdown characteristics (THS6053 only)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VIL(SHDN)	Shutdown pin voltage for power up	$V_{CC} = \pm 6 \text{ V}, \pm 12 \text{ V} \text{ GND} = 0 \text{ V},$ (GND Pin as Reference)			0.8	V
VIH(SHDN)	Shutdown pin voltage for power down	$V_{CC} = \pm 6 \text{ V}, \pm 12 \text{ V}, \text{ GND} = 0 \text{ V},$ (GND Pin as Reference)	2			V
ICC(SHDN)	Total quiescent current when in shutdown state	$V_{GND} = 0 \text{ V}, V_{CC} = \pm 6 \text{ V}, \pm 12 \text{ V}$		0.3	0.7	mA
tDIS	Disable time (see Note 3)	V _{CC} = ±12 V		0.1		μs
t _{EN}	Enable time (see Note 3)	V _{CC} = ±12 V		0.4		μs
I _{IL} (SHDN)	Shutdown pin input bias current for power up	V _{CC} = ±6 V, ±12 V		40	100	μΑ
I _{IH} (SHDN)	Shutdown pin input bias current for power down	V _{CC} = ±6 V, ±12 V, V(SHND) = 3.3 V		50	100	μΑ

NOTE 3: Disable/enable time is defined as the time from when the shutdown signal is applied to the SHDN pin to when the supply current has reached half of its final value.

APPLICATION INFORMATION

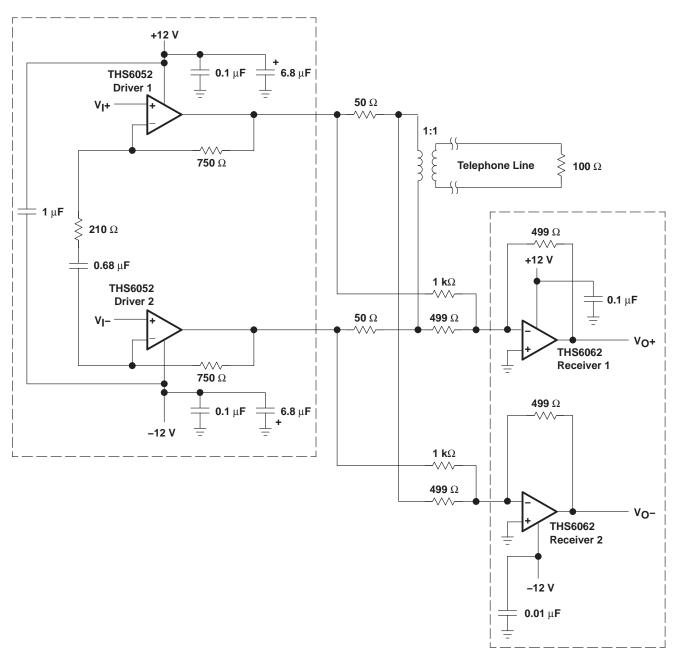


Figure 1. THS6052 ADSL Application With 1:1 Transformer Ratio







10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
THS6052CDDA	ACTIVE	SO PowerPAD	DDA	8	75	RoHS & Green	SN	Level-1-260C-UNLIM	0 to 70	6052C	Samples
THS6052ID	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	60521	Samples
THS6052IDDA	ACTIVE	SO PowerPAD	DDA	8	75	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 85	60521	Samples
THS6053CPWPR	ACTIVE	HTSSOP	PWP	14	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	0 to 70	HS6053C	Samples
THS6053IPWP	ACTIVE	HTSSOP	PWP	14	90	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	HS6053I	Samples
THS6053IPWPR	ACTIVE	HTSSOP	PWP	14	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	HS6053I	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

10-Dec-2020

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
THS6053CPWPR	HTSSOP	PWP	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
THS6053IPWPR	HTSSOP	PWP	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins SPQ		Length (mm)	Width (mm)	Height (mm)	
THS6053CPWPR	HTSSOP	PWP	14	2000	350.0	350.0	43.0	
THS6053IPWPR	HTSSOP	PWP	14	2000	350.0	350.0	43.0	

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
THS6052CDDA	DDA	HSOIC	8	75	505.46	6.76	3810	4
THS6052ID	D	SOIC	8	75	505.46	6.76	3810	4
THS6052IDDA	DDA	HSOIC	8	75	505.46	6.76	3810	4
THS6053IPWP	PWP	HTSSOP	14	90	530	10.2	3600	3.5



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4202561/G



4.4 x 5.0, 0.65 mm pitch

PLASTIC SMALL OUTLINE

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



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